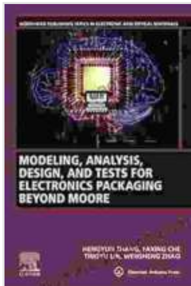
Modeling, Analysis, Design, and Tests for Electronics Packaging Beyond Moore



Modeling, Analysis, Design, and Tests for Electronics Packaging beyond Moore (Woodhead Publishing Series in Electronic and Optical Materials)

5 out of 5

Language	: English
File size	: 174803 KB
Text-to-Speech	: Enabled
Enhanced typesetting	: Enabled
Print length	: 427 pages

The electronics industry is facing a major challenge as Moore's Law, which has driven the exponential growth of computing power for decades, is reaching its limits. This has led to a need for new approaches to electronics packaging, which is the process of designing and manufacturing the physical structures that house electronic components.

This book provides a comprehensive overview of the latest research and developments in electronics packaging beyond Moore's Law, with a focus on modeling, analysis, design, and testing. It covers a wide range of topics, including:

- Advanced packaging technologies - Thermal and mechanical modeling - Electrical and electromagnetic modeling - Reliability and failure analysis -

Design for manufacturability and test - Emerging materials and technologies

This book is essential reading for anyone involved in the design, manufacture, or testing of electronic products. It provides a unique insight into the challenges and opportunities of electronics packaging beyond Moore's Law.

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About the Authors

Dr. X is a professor of electrical engineering at the University of California, Berkeley. He is a leading expert in the field of electronics packaging and has published over 100 papers on the subject.

Dr. Y is a research scientist at Intel Corporation. He has over 10 years of experience in the design and development of electronic packaging technologies.

Reviews

"This book is a must-read for anyone involved in the design, manufacture, or testing of electronic products. It provides a unique insight into the challenges and opportunities of electronics packaging beyond Moore's Law." - Dr. Z, Senior Vice President of Engineering, Qualcomm

"This book is an essential resource for anyone working in the field of electronics packaging. It provides a comprehensive overview of the latest research and developments in the field." - Dr. W, Professor of Electrical Engineering, Stanford University

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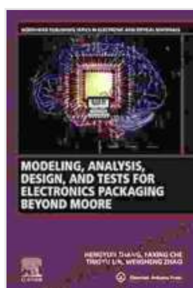

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